

ABSTRACT

The present invention provides a substrate holding apparatus, comprising: a cup, configured to carry a substrate; a pressure plate, configured to press against the back surface of the substrate to secure the substrate relative to the cup, for holding the substrate; a pressure plate driving device, connected to the pressure plate, configured to drive the pressure plate to descend or ascend, so that the pressure plate presses against the back surface of the substrate to clamp the substrate, or the pressure plate leaves the back surface of the substrate; and a sealing member, arranged on the pressure plate, including a fixing portion configured to secure the sealing member on the pressure plate and a first sealing portion protruding downward from the fixing portion, wherein the cross-sectional shape of the first sealing portion is the same as the cross-sectional shape of the gap between the peripheral side of the pressure plate and the cup when the pressure plate abuts against the cup, and the first sealing portion abuts against the upper end surface of the cup when pressed by the pressure plate, so as to define a sealing area. Under the combined action of the first sealing portion, the second sealing portion, and the third sealing portion of the sealing member, the present invention forms multiple seals, and the sealing effect is further ensured, thereby ensuring the electroplating quality.